### Dual N-Channel 60V, 22.5mΩ Typ. Power MOSFET

## **Description**

#### **Features**

• 60V, 18A

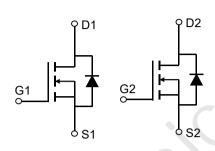
$$R_{DS(ON)}$$
 Typ = 22.5m $\Omega$  @  $V_{GS}$  = 10V

$$R_{DS(ON)}$$
 Typ = 25.6m $\Omega$  @  $V_{GS}$  = 4.5V

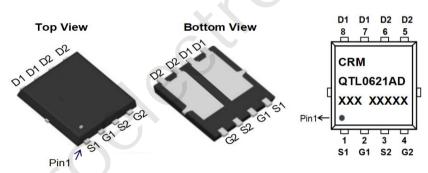
- Advanced Trench Technology
- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔVds TESTED!

## **Application**

- Load Switch
- PWM Application
- Power Management







**Marking and Pin Assignment** 

### **Package Marking and Ordering Information**

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQTL0621AD	CRMQTL0621AD	PDFN3.3x3.3-8L-D	TAPING	13"	5000	50000

#### Absolute Maximum Ratings (@ T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		60	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Ocation of Desire Comment	T <sub>C</sub> = 25°C	18	Α
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 100°C	10.8	Α
I <sub>DM</sub>	Pulsed Drain Current (1)		72	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)		25	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C	17	W
$R_{ hetaJC}$	Thermal Resistance, Junction to Case		7.3	°C/W
$T_J,T_STG$	Junction & Storage Temperature Range		-55 to 150	°C



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### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
Off Chara	acteristics					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.5	2.3	V
	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	22.5	29	mΩ
$R_{DS(ON)}$		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A	-	25.6	33	mΩ
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance			1035	-	pF
$C_{oss}$	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V,$ f = 1MHz	X -	65	-	pF
$C_{rss}$	Reverse Transfer Capacitance	· ·····-		60	-	pF
Q <sub>g</sub>	Total Gate Charge		<u></u> -	25	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 30V, I_{D} = 5A$	-	4.5	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	v <sub>DS</sub> - 30 v, i <sub>D</sub> - 3A	-	6.5	-	nC
Switchin	g Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	7	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 30V$	-	20	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 20A$ , $R_{GEN} = 3\Omega$	-	16	-	ns
$t_{f}$	Turn-Off Fall Time		-	23	-	ns
Drain-So	urce Diode Characteristics and M	lax Ratings				
Is	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	18	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	72	А
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 10A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	29	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 5A$ , di/dt = 100A/us	_	49	_	nC

Notes:

<sup>1.</sup> Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

<sup>2.</sup>  $E_{AS}$  condition: Starting  $T_J$ =25°C,  $V_{DD}$ =30V,  $V_G$ =10V,  $R_G$ =25ohm, L=0.5mH,  $I_{AS}$ =10A

<sup>3.</sup> Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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### **Test Circuit**

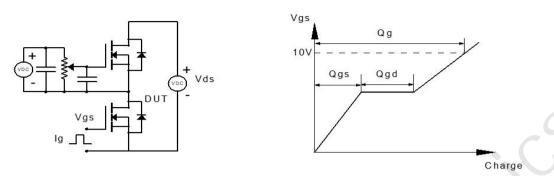


Figure 1: Gate Charge Test Circuit & Waveform

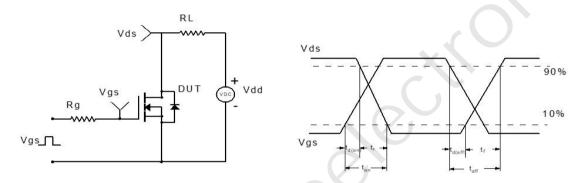


Figure 2: Resistive Switching Test Circuit & Waveform

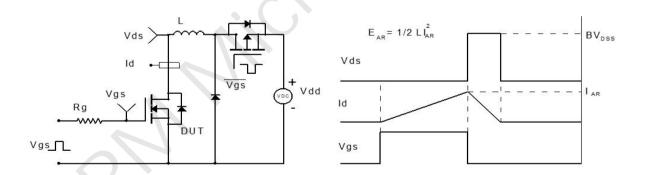


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

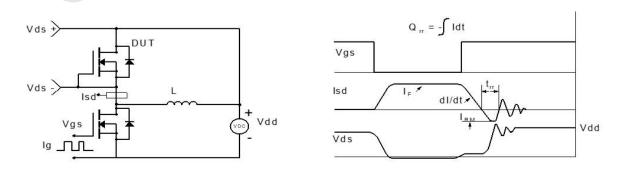
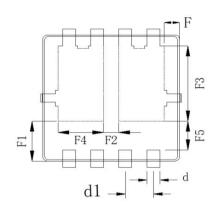
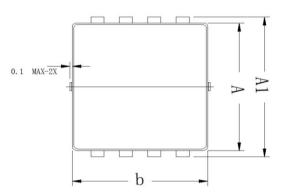


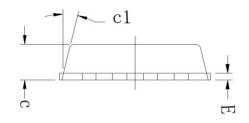
Figure 4: Diode Recovery Test Circuit & Waveform

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## Package Mechanical Data(PDFN3.3x3.3-8L-D)







	COMMON DIM	IENSION (MM)	
PKG	PDFN 3.3×3.3-8L-D		
SYMBOL	MIN	TYP	MAX
А	3. 070	3.100	3.130
A1	3, 300	3.400	3.500
b	3. 070	3. 100	3. 130
С	0.770	0.800	0.830
c1	100	13°	=3
d	0. 275	0.300	0.325
d1	0.625	0.650	0. 675
Е	0. 144	0. 152	0. 160
F	0.300	0. 325	0. 350
F1	0. 960	0. 985	1.010
F2	0. 355	0. 380	0. 405
F3	1. 775	1. 800	1.825
F4	1. 010	1. 035	1.060
F5	0.660	0. 685	0.710

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